

CLAIMS

1. A method of forming a semiconductor package comprising:

- 5 providing a leadframe having a main panel, a cavity section, and a plurality of leads extending from the main panel into the cavity section, the main panel no greater than a first distance from an outer edge of the cavity section and at least a first lead of the plurality of
10 leads extending no greater than the first distance from the cavity section toward the main panel;
encapsulating the cavity section of the leadframe to form a package body;
forming a first portion of the main panel into a
15 portion of the first lead including forming the portion of the first lead extending greater than the first distance from the package body; and
excising a second portion of the main panel away from the first lead.

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2. The method of claim 1 wherein providing the leadframe having the main panel, the cavity section, and the plurality of leads extending from the main panel into the cavity section, the main panel no greater than the
25 first distance from an outer edge of the cavity section includes forming the first distance no greater than approximately 0.5 millimeters.

3. The method of claim 1 wherein excising the second
30 portion of the main panel away from the first lead includes leaving a third portion of the main panel attached to an end of at least one lead of the plurality of leads.

- 35 4. The method of claim 3 further including plating exposed portions of the plurality of leads.

5. The method of claim 4 further including excising the end of the at least one lead of the plurality of leads from the main panel after plating exposed portions of the plurality of leads.

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6. The method of claim 1 wherein forming the first portion of the main panel into the portion of the first lead of the plurality of leads includes trimming the main panel to form the portion of the plurality of leads.

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7. The method of claim 1 wherein forming the first portion of the main panel into the portion of the first lead of the plurality of leads includes forming the portion of the first lead extending no greater than about 0.5 millimeters from the package body.

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8. The method of claim 1 further including plating the plurality of leads and the main panel prior to the step of forming the first portion of the main panel into the portion of the first lead.

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9. The method of claim 1 wherein forming the first portion of the main panel into the portion of the first lead of the plurality of leads includes selectively forming the first portion of the main panel into a number of leads that is less than all of the plurality of leads.

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10. The method of claim 1 wherein forming the first portion of the main panel into the portion of the first lead of the plurality of leads includes forming the first portion of the main panel into a number of leads that is equal to all of the plurality of leads.

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11. The method of claim 1 wherein providing the leadframe having the main panel, the cavity section, and the plurality of leads extending from the main panel into the cavity section, the main panel no greater than the
5 first distance from the outer edge of the cavity section includes forming the leadframe devoid of a dam-bar between the main panel and the cavity section.

12. A leadframe for a semiconductor package
10 comprising:
a main panel having a plurality of cavity sections, the main panel no greater than a first distance from an outer edge of a cavity section of the plurality of cavity sections; and
15 a plurality of leads extending from the main panel into the cavity section of the plurality of cavity sections, the plurality of leads extending no greater than the first distance from the outer edge of the cavity section of the plurality of cavity sections toward the
20 main panel.

13. The leadframe of claim 12 wherein the main panel having the plurality of cavity sections, the main panel no greater than the first distance from the outer edge of the
25 cavity section of the plurality of cavity sections includes the first distance no greater than 0.5 millimeters.

14. The leadframe of claim 12 further including the
30 leadframe devoid of a dam-bar between the main panel and the cavity section.

15. A method of forming a leadframe for a semiconductor package comprising:

forming a leadframe strip having a main panel and a plurality of cavity sections

5 forming the main panel no greater than a first distance from an outer edge of a cavity section of the plurality of cavity sections; and

forming a plurality of leads extending from the main panel into a cavity section of the plurality of cavity sections including forming the leads extending no greater
10 than the first distance from the cavity section of the plurality of cavity sections toward the main panel.

16. The method of claim 15 wherein forming the main
15 panel no greater than the first distance from the outer edge of the cavity section of the plurality of cavity sections includes forming the first distance no greater than 0.5 millimeters.

20 17. The method of claim 15 further including forming the leadframe devoid of a dam-bar between the main panel and the cavity section.